



**For preheat,
rework and
reflow!**

**Lead Free*
High Temp
Option!!**

Standard Model: GF-DL dual hot plate
Lead Free Model: GF-DL-HT

Used for a variety of heating applications which include preheat, rework, reflow and curing of printed circuit board assemblies.



Standard Model: GF-SL single hot plate
Lead Free Model: GF-SL-HT

GF-SL/DL Features:

- Lead free capable option: HT model
 - Large 13" x 13" heating area
 - 3/4" thick aluminum heat plates for precise, even heating
 - Programmable digital temperature controller precisely and automatically regulates temperatures
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- Model **GF-DL** is the same as **GF-SL** above but with two independent temperature controls and dual 13" x 6.4" plates.

Model GF-DL SPECIFICATIONS	
Electrical Power**	110 VAC, 50/60, 20A
Power	900 W each plate
Temperature Range Standard model: GF-DL	100° to 482°F (37° to 250°C)
Temperature Range High Temp: GF-DL-HT	100° to 600°F (37° to 315°C)
Heating Area (x2)	13" x 6.4" (330x163mm)
Dimensions	22.63" x 15.75" x 4.50" (575 x 400 x 114 mm)
Approximate Weight	35 lbs (16Kg)

Model GF-SL SPECIFICATIONS	
Electrical Power**	110 VAC, 50/60,
Power	1800 W
Temperature Range Standard model: GF-SL	100° to 482°F (37° to 250°C)
Temperature Range High Temp: GF-SL-HT	100° to 600°F (37° to 315°C)
Heating Area	13" x 13" (330x330mm)
Dimensions	22.63" x 15.75" x 4.50" (575 x 400 x 114 mm)
Approximate Weight	35 lbs (16Kg)

*For use with lead free solder alloys.
**Other electrical configurations available.